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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Eng-Chew Cheah

Application No.: 09/863,652

Filed: May 22, 2001

For: *Multi-Tiered Lead Package For An
Integrated Circuit*

Group Art Unit: 2827

Examiner: David A. Zarneke

Attorney Docket No.: 9818-0050-999

Date: May 6, 2002

Response to Restriction Requirement

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This communication is responsive to the Restriction Requirement mailed April 5, 2002.

Amendment

IN THE CLAIMS:

Please cancel claims 14-19 without prejudice.

Please add the following new claims:

20. (NEW) A semiconductor package, comprising:

a semiconductor die with a bond pad;

a package lead;

a bond wire comprising a first end portion coupled to the package lead, a second end portion coupled to the bond pad, and an intermediate portion; and

an intermediate lead finger positioned between the package lead and the bond pad, the intermediate lead finger affixing at least part of the intermediate portion of the bond wire at a position between the semiconductor die and the package lead.

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21. (NEW) The package of claim 20, further comprising an intermediate lead finger mounting substrate, wherein the intermediate lead finger is mounted on the intermediate lead finger mounting substrate.

22. (NEW) The package of claim 20, wherein the intermediate lead finger and the intermediate lead finger mounting substrate are formed of a non-conducting material.

23. (NEW) The package of claim 22, further comprising a die attachment pad attached to the intermediate lead finger mounting substrate.

B 24. (NEW) The package of claim 23, wherein the die attachment pad is made of a heat-conducting material for rapid heat dissipation.

25. (NEW) The package of claim 23, further comprising a mold compound that encloses the semiconductor die, a portion of the package lead, the bond wire, the intermediate lead finger, and the die attachment pad.

26. (NEW) The package of claim 20, wherein the intermediate lead finger comprises a non-conducting portion for attaching to the intermediate portion of the bond wire.

27. (NEW) The package of claim 20, wherein the semiconductor die comprises a programmable logic device.

Remarks

Restriction Requirement

The Office Action of April 5, 2002, imposed a restriction between:

- I. Claims 1-13, drawn to a package, classified in class 257, subclass 1+; and
- II. Claims 14-19 are drawn to a method, classified in class 438, subclass 106+.

Applicant hereby elects claims 1-13 of Group I without traverse.

New claims 20-27

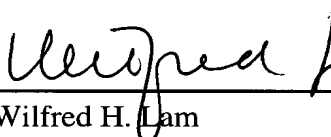
New claims 20-27 are presented for examination. Support for claims 20-27 are supported by Figs. 1A-1C and Fig. 2 and their corresponding description in the specification.

The Examiner is invited to call the undersigned representative if there is any questions regarding this Amendment.

The Commissioner is hereby authorized to charge any required fees or credit any overpayment to Deposit Account No. 16-1150 (Order No. 9818-0050-999). This form is submitted in duplicate for such purpose.

Respectfully submitted,

Date May 6, 2002

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